

S/N: 09/832,884

6/4/2001

DOCKET NO.: L/M-102-DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Stev M. Danziger, t al.

Serial No.: 09/832,884

Art Unit: 2813

Divisional of 09/321,565

Filed: April 12, 2001

Examiner: TO BE ASSIGNED

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects



INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §§ 1.56, 1.97, and 1.98

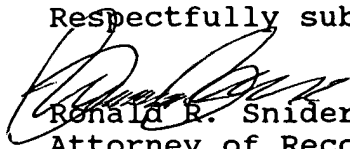
Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Sir:

In compliance with the dictates of 37 C.F.R. §§ 1.56, 1.97, and 1.98, Applicant hereby submits an Information Disclosure Statement.

The referenced documents were previously cited by or submitted to the USPTO in the parent application 09/321,565 (now issued US Patent No. 6,221,682) and copies may be found therein. The attached listing is submitted with the desire that the Examiner consider the information and that the references considered be printed on any resulting patent. It is respectfully requested that the Examiner indicate such consideration by enclosing an appropriately initialed copy of the enclosed form PTO-1449 with the next communication from the Patent Office.

Respectfully submitted,


Ronald R. Snider
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Date: June 4, 2001

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